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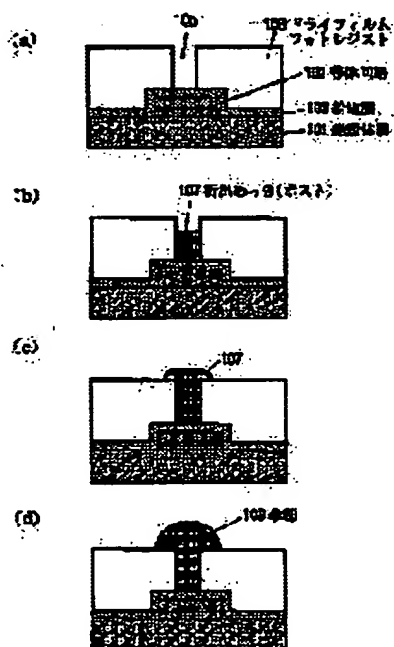
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## (54) PRINTED WIRING BOARD, MANUFACTURE THEREOF AND ELEMENT MOUNTING METHOD

### (57)Abstract:

**PROBLEM TO BE SOLVED:** To form mounting pads and metal posts at once with a single electrolytic plating by integrating the mounting pads with the metal posts piercing an insulation film of a printed wiring board having conductor circuit layer laminated through the insulation layer; the posts being electrically connecting conductor circuits.

**SOLUTION:** The deposition plating 107 is limited about its depositing direction by a dry film photoresist 106 such that it expands over this film 106 upward and in horizontal direction to finally form hoods 108 at the top ends of posts 107. After the plating runs over the resist 106, it spreads in all directions to result in semi-spherical hoods 108 for circular columnar posts 107, thereby forming mounting pads. Thus the single electrolytic plating forms pots and mounting pads at the same time.



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